

### **SPECIFICATION SHEET**

SPECIFICATION SHEET NO.	R0610- 2SD1664S80SDAP	
DATE	June 10, 2024	
REVISION	A2	Updated With Most Recent Data
DESCRIPTION AND	SMD Plastic-Encapsulate Transistors, 3 Pads, Case SOT-89-3L 2SD Series, Transistor Type NPN	
MAIN PARAMETRICS	hfe Rank	Range 82~180
	Collector	-Base Voltage 40V Max. Collector Current 1A Max.
	Operating Temp. Range -55°C ~+150°C	
	Package in Tape/Reel, 1000pcs/Reel	
	RoHS III/REACH Compliant and Halogen Free (HF)	
	NOTS III/NEACT COMPILATE AND HAIOSEN FIEE (HF)	
CUSTOMER		
CUSTOMER PART NO.		
CROSS REF. PART NO.		
ORIGINAL MFG/PART NO.	MDD Diodes/2SD1664-DAP	
PART CODE	2SD1664S80SDAP	

### **VENDOR APPROVE**

Issued/Checked/Approved

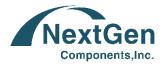






DATE: June 10, 2024

CUSTOMER APPROVE	
DATE:	



### **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

#### **MAIN FEATURE**

- · Epoxy Meets UL-94 V-0 Flammability Rating
- Low Vce(sat), Vce(sat)=0.15V (Typ.) @Ic=0.5A, IB=50mA
- Complementary PNP Type Available (Part Code 2SB1132S80SBAP)
- Surface Mount Package Ideally Suited for Automatic Insertion
- REACH/RoHS III Complaint and Halogen Free
- Cross Main Competitor Parts in Market

#### **APPLICATION**

For SMD application

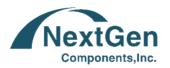
#### **ELECTRICAL CHARACTERISTICS**

- See Page 4~ Page 5
- HOW TO ORDER
- Please Follow Up Part Code Guide And Indicate Pat Code When You Order Or RFQ For Custom Specification.

#### **PART CODE GUIDE**



CODE	NAME	KEY SPECIFICATION OPTION
2SD	Product Series Code	SMD Plastic-Encapsulate Transistors 2SD series
1164	Specification Code	For Original Part Number 2SD1164
S8	Case Code	S8: Case SOT-89-3L
OS	Internal Control Code	Custom letter A~Z, a-z or Digits (0-9)
DAP	Marking Code	Custom letter A~Z, a-z or Digits (0-9) for Different Part Code



# **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

**DIMENSION** (Unit: Inch/mm)

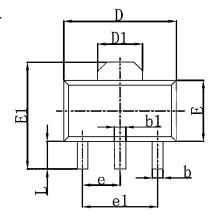
### Image for reference

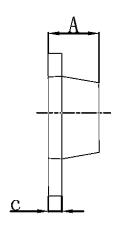


#### Marking:

See Page 4 - Marking List For different Part code

#### SOT-89-3L

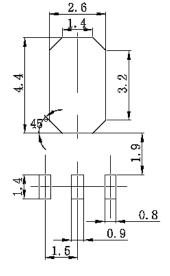




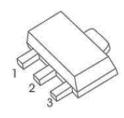
Symbol	Value ( mm)		
	Min.	Тур.	Max.
А	1.4		1.6
b	0.32		0.52
b1	0.40		0.58
С	0.35		0.44
D	4.4		4.6
E	2.3		2.60
E1	3.94		4.25
е		1.5	
e1		3.0	
L	0.90		1.20

### **Recommend Pad Layout**

Tolerance: ±0.05mm



#### **Pin Function**



- 1. Base
- 2. Emitter
- 3. Collector

3



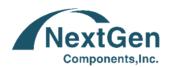
## **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

#### **CLASSIFICATION OF hFE**

PART CODE	RANK CODE	RANK RANG	MARKING
2SD1664S80SDAP	Р	82~180	DAP
2SD1664S80SDAQ	Q	120~270	DAQ
2SD1664S80SDAR	R	180~390	DAR

#### MAXIMUM RATINGS - @ 25 °C

PARAMETER	SYMBOLS	VALUE	UNITS
Collector-Base Voltage	VCBO	40	Volts
Collector-Emitter Voltage	VCEO	32	Volts
Emitter-Base Voltage	VEBO	5	Volts
Collector Current -Continuous	Ic	1	А
Collector Power Dissipation	Рс	0.5	W
Thermal Resistance From Junction To Ambient	Røja	500	°C/W
Junction Temperature	TJ	+150	°C
Storage Temperature Range	Тѕтб	-55 ~ +150	°C



## **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

### **ELECTRICAL CHARACTERISTICS**- @ 25 °C

PARAMETER	SYMBOLS	VALUE		UNIT	TEST CONDITION	
		MIN.	TYP.	MAX.		
Collector-base Breakdown Voltage	V(BR)CBO	40			V	Ic= 50μA, IE=0
Collector-emitter Breakdown Voltage	V(BR)CEO	32			V	Ic= 1mA, IB=0
Emitter-base Breakdown Voltage	V(BR)EBO	5			V	IE= 50μA, IC=0
Collector Base Cut-off Current	Ісво			0.5	μΑ	VCB= 20V, IE=0
Emitter Base Cut-off Current	IEBO			0.5	μΑ	VEB= 4V, IC=0
DC Current Gain	hFE	82		390		VCE=3V, IC=0.1A
Collector-emitter Saturation Voltage	VCE(sat)			0.4	V	IC=0.5A, IB=50mA
Transition Frequency	fτ		150		MHz	VCE=5V, IC= 50mA, f=100MHz
Collector Output Capacitance	Cob		15		pF	VCB=10V, IE=0, f=1MHz



# SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L

Fig.1

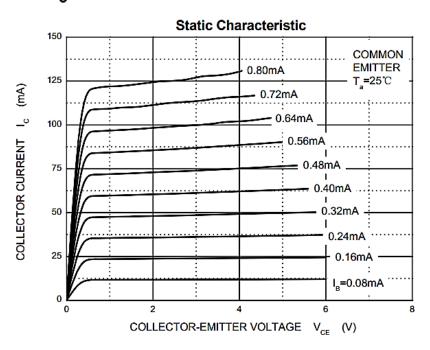
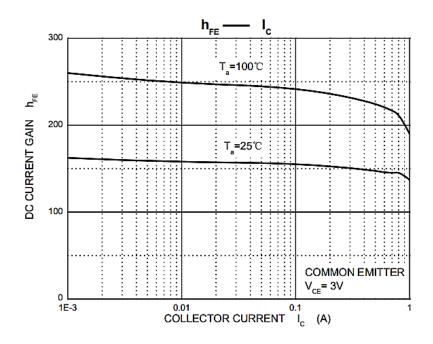
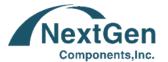
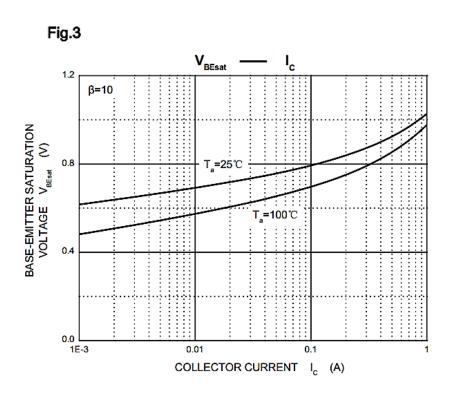


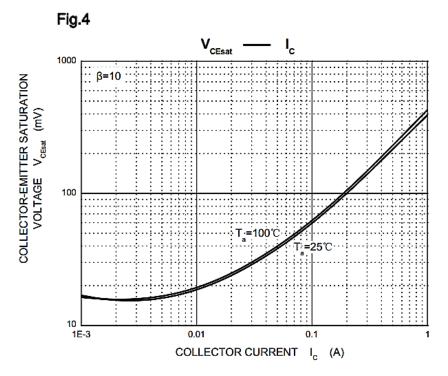
Fig.2



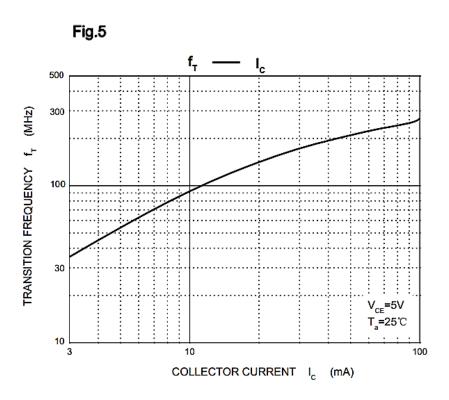


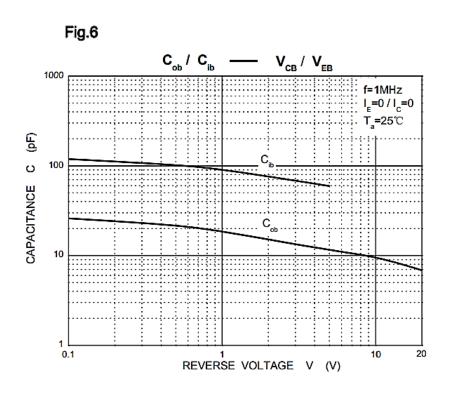
### **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

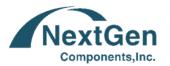




### **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

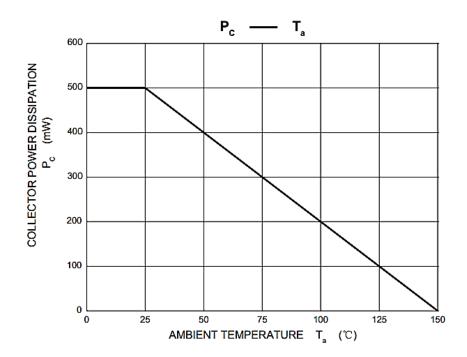






### **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

Fig.7





# **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

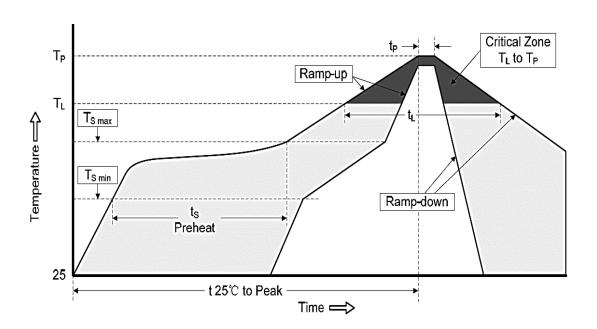
### **RELIABILITY**

Number	Experiment Items	Experiment Method And Conditions	Reference Documents
1	Solder Resistance Test	Test 260°C± 5°C for 10 ± 2 sec. Immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031.2
2	Solderability Test	230°C ±5°C for 5 sec.	MIL-STD-750D METHOD-2026.1 0
3	Pull Test	1 kg in axial lead direction for 10 sec.	MIL-STD-750D METHOD-2036.4
4	Bend Test	0.5Kg Weight Applied To Each Lead, Bending Arcs 90 °C ± 5 °C For 3 Times	MIL-STD-750D METHOD-2036.4
5	High Temperature Reverse Bias Test	TA=100°C for 1000 Hours at VR=80% Rated VR	MIL-STD-750D METHOD-1038.4
6	Forward Operation Life Test	TA=25°C Rated Average Rectified Current	MIL-STD-750D METHOD-1027.3
7	Intermittent Operation Life Test	On state: 5 min with rated IRMS Power Off state: 5 min with Cool Forced Air. On and off for 1000 cycles.	MIL-STD-750D METHOD-1036.3
8	Pressure Cooker Test	15 PSIG, Ta=121°C, 4 hours	MIL-S-19500 APPENOIXC
9	Temperature Cycling Test	-55°C~+125°C; 30 Minutes For Dwelled Time 5 minutes for transferred time. Total: 10 cycles.	MIL-STD-750D METHOD-1051.7
10	Thermal Shock Test	0°C for 5 minutes., 100°C for 5minutes, Total: 10 cycles	MIL-STD-750D METHOD-1056.7
11	Forward Surge Test	8.3ms Single Sale Sine-wave One Surge.	MIL-STD-750D METHOD-4066.4
12	Humidity Test	Ta=65°C, RH=98% for 1000 hours.	MIL-STD-750D METHOD-1021.3
13	High Temperature Storage life Test	150°C for 1000 Hours	MIL-STD-750D METHOD-1031.5

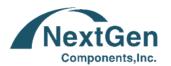


### **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

### **SUGGESTED REFLOW PROFILE** - For Reference Only



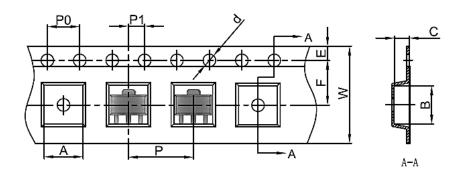
PROFILE FEATURE		PB-FREE ASSEMBLY
Average Ramp-up Rate (Ts Max to Tp)		3°C/second Max
Preheat	Temperature Min (Ts Min.)	150°C
	Temperature Max (Ts Max.)	200°C
	Time (ts Min. to ts Max.)	60 ~ 180 seconds
Time maintained above	Temperature (TL)	217°C
	Time (tL)	60 ~ 150 seconds
Peak/Classification Temperature (Tp)		260 °C
Time within 5°C of actual Peak Temperature (tp)		20 ~ 40 seconds
Ramp-down rate		6 °C /Second Max.
Time 25 °C to Peak Temperature		8 minutes Max.
Suggest reflow times		3 Times Max.

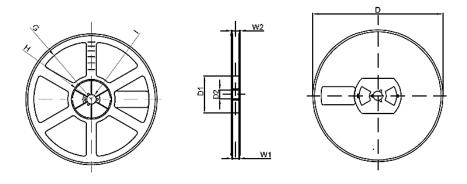


### **SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L**

#### TAPE/REEL - Unit: mm

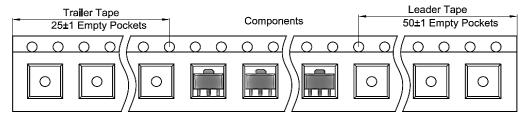
All Devices are packed in accordance with EIA standard RS-481-A and specifications. SOT-89-3L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and antistatic sprayed agent. These reeled parts In standard option are shipped with 1,000 units per 7" or 18cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).





Symbol	Dimension (mm)
А	4.85±0.1
В	4.45±0.1
С	1.85±0.1
d	φ1.50±0.1
E	1.75±0.1
F	5.50±0.1
P 0	4.00±0.1
Р	8.00±0.1
P 1	2.00±0.1
W	12.00±0.1
D	ф178±2
D1	54.4±1
D2	13.0±1
G	R78±1
Н	R25.6±1
Ţ	R6.5±1
W 1	13.20±1
W2	16.50±1

### **TAPE LEADER AND TRAILER**





### SMD TRANSISTORS 2SD SERIES CASE SOT-89-3L

#### IMPORTANT NOTES AND DISCLAIMER

- ROHS COMPLIANCE: The levels of RoHS restricted materials in this product are below the maximum
  concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an
  exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for
  this product can be obtained can be obtained at Download Center.
- REACH COMPLIANCE: REACH substances of high concern (SVHCs) information is available for this product.
   Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained can be obtained at Download Center.
- All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test
  conditions, unless otherwise noted. Product performance may not be indicated by the Electrical
  Characteristics if operated under different conditions.
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  express written approval by NextGen.
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Non-Cancelable/ Non-Returnable (NCNR). These products are not returnable and not refundable. 6/10/2024